

Fast switching diode chip in EMCON-Technology

FEATURES:

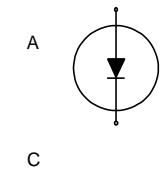
- 1200V EMCON technology 130 µm chip
- soft, fast switching
- low reverse recovery charge
- small temperature coefficient

This chip is used for:

- EUPEC power modules and discrete devices

Applications:

- SMPS, resonant applications, drives



Chip Type	V _R	I _F	Die Size	Package	Ordering Code
SIDC14D120E6	1200V	15A	3.8 x 3.8 mm ²	sawn on foil	Q67050-A4123-A001

MECHANICAL PARAMETER:

Raster size	3.8 x 3.8	mm ²
Area total / active	14.44 / 9.8	
Anode pad size	3.08 x 3.08	
Thickness	130	µm
Wafer size	150	mm
Flat position	180	deg
Max. possible chips per wafer	1018 pcs	
Passivation frontside	Photoimide	
Anode metallisation	3200 nm Al Si 1%	
Cathode metallisation	1400 nm Ni Ag –system suitable for epoxy and soft solder die bonding	
Die bond	electrically conductive glue or solder	
Wire bond	Al, ≤500µm	
Reject Ink Dot Size	Ø 0.65mm ; max 1.2mm	
Recommended Storage Environment	store in original container, in dry nitrogen, < 6 month at an ambient temperature of 23°C	

Maximum Ratings

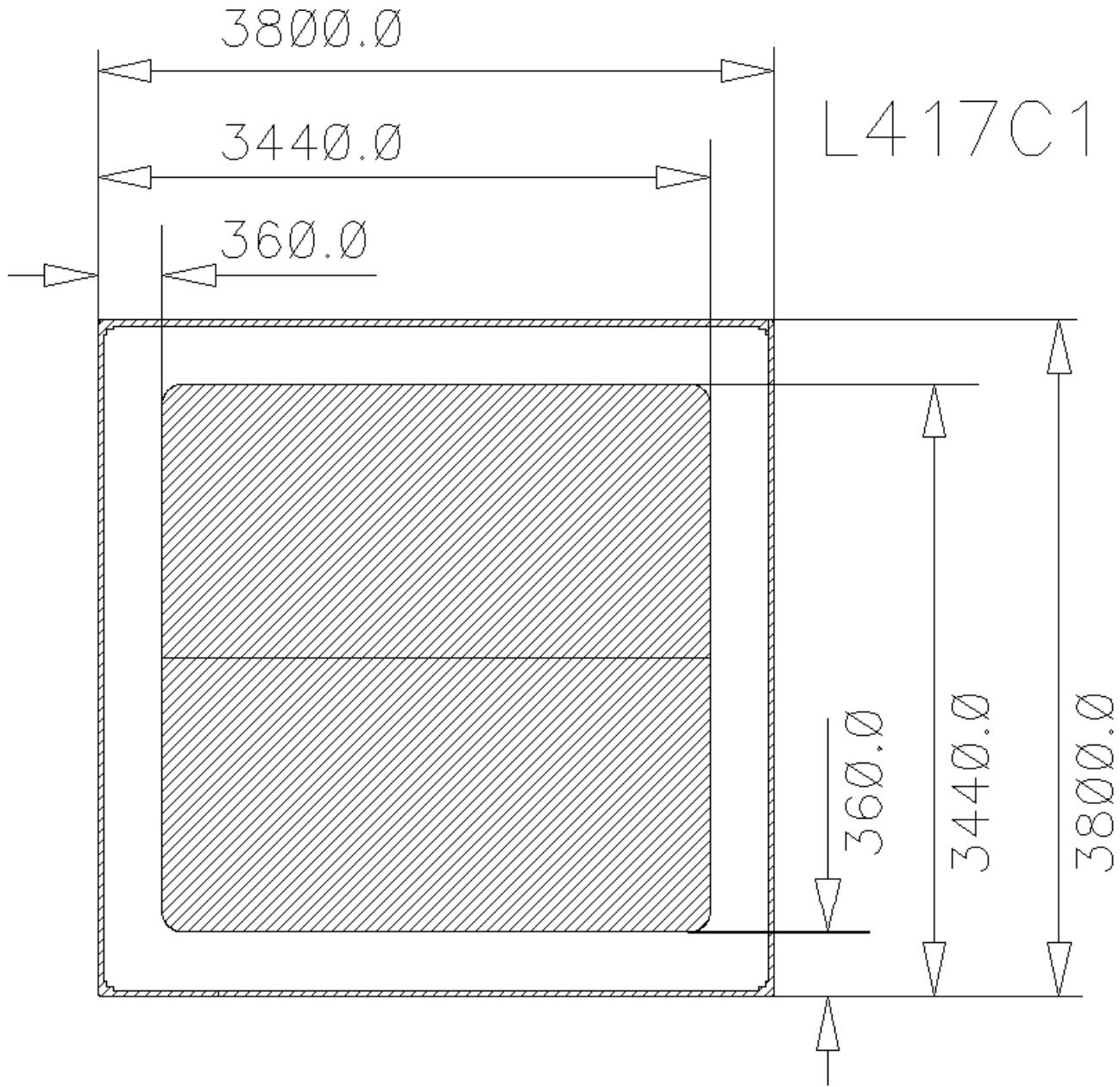
Parameter	Symbol	Condition	Value	Unit
Repetitive peak reverse voltage	V_{RRM}		1200	V
Continuous forward current limited by T_{jmax}	I_F		15	A
Single pulse forward current (depending on wire bond configuration)	I_{FSM}	$t_P = 10 \text{ ms sinusoidal}$	tbd	
Maximum repetitive forward current limited by T_{jmax}	I_{FRM}		30	
Operating junction and storage temperature	T_j, T_{stg}		-55...+150	°C

Static Electrical Characteristics (tested on chip), $T_j=25 \text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions		Value			Unit
				min.	Typ.	max.	
Reverse leakage current	I_R	$V_R=1200V$	$T_j=25 \text{ °C}$			250	µA
Cathode-Anode breakdown Voltage	V_{Br}	$I_R=1mA$	$T_j=25 \text{ °C}$	1200			V
Forward voltage drop	V_F	$I_F=15A$	$T_j=25 \text{ °C}$		1.9		V

Dynamic Electrical Characteristics, at $T_j = 25 \text{ °C}$, unless otherwise specified, tested at component

Parameter	Symbol	Conditions		Value			Unit
				min.	Typ.	max.	
Reverse recovery time	t_{rr1}	$I_F=15A$ $di/dt=390A/\text{ms}$ $V_R=600V$	$T_j = 25 \text{ °C}$		tbd		ns
	t_{rr2}		$T_j = 125 \text{ °C}$				
Peak recovery current	I_{RRM1}	$I_F=15A$ $di/dt=390A/\text{ms}$ $V_R= 600V$	$T_j = 25 \text{ °C}$		10.9		A
	I_{RRM2}		$T_j = 125 \text{ °C}$		14.5		
Reverse recovery charge	Q_{rr1}	$I_F=15A$ $di/dt=390A/\text{ms}$ $V_R= 600V$	$T_j=25 \text{ °C}$		1.45		µC
	Q_{rr2}		$T_j=125 \text{ °C}$		3.23		
Peak rate of fall of reverse recovery current	di_{rr1}/dt	$I_F=15A$ $di/dt=390A/\text{ms}$ $V_R= 600V$	$T_j=25 \text{ °C}$		tbd		A/µs
	di_{rr2}/dt		$T_j=125 \text{ °C}$				
Softness	S1	$I_F=15A$ $di/dt=390A/\text{ms}$ $V_R= 600V$	$T_j=25 \text{ °C}$		tbd		1
	S2		$T_j=125 \text{ °C}$				

CHIP DRAWING:

Flatside



1 mm

all measurements in μm

**FURTHER ELECTRICAL CHARACTERISTICS:**

This chip data sheet refers to the
device data sheet

INFINEON TECHNOLOGIES /
EUPEC

tbd

Description:

AQL 0,65 for visual inspection according to failure catalog

Electrostatic Discharge Sensitive Device according to MIL-STD 883

Test-Normen Villach/Prüffeld

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